

09-11-2007



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RECORDATION FORM COVER SHEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

PATENTS ONLY

Attorney Docket Number **H0015391-0769**

8-29-07

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original assignment document.

1. Name of all Party(ies) conveying an interest:

- 1. Michael E. Moran
- 2. Sean D. Gregory
- 3. Jason R. Robinson
- 4. John Liu

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and Address of receiving Party(ies):

Honeywell International Inc.
101 Columbia Road
P.O. Box 2245
AB-2B
Morristown, NJ 07962

Additional name(s) and address(es) attached? Yes No

3. Nature of Conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Assignment Execution Date(s):

- August 22, 2007
- August 20, 2007
- August 21, 2007
- August 20, 2007

Title: **Active Temperature Differential Compensation for Strain Gage Based Sensors**

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

- August 22, 2007
- August 20, 2007
- August 21, 2007
- August 20, 2007

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and Address of party to whom correspondence concerning document should be mailed:

PATENT SERVICES
Honeywell International Inc.
101 Columbia Road
P.O. Box 2245
AB-2B
Morristown, NJ 07962

6. Total number of applications and patents involved = **1**

7. Total Fee (37 CFR 3.41): **\$ 40.00**

- Enclosed
- Authorized to be charged to Deposit Account

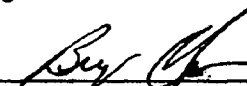
8. Deposit Account Number: **01-1125**

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Name of Person Signing
Bryan Anderson



 Signature

Date **August 27, 2007**

Total number of pages comprising cover sheet: 1

09/10/2007 MJAMA1 00000108 011125 11897158

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ASSIGNMENT


WHEREAS, I, **Michael E. Moran**, City of Marysville, State of Ohio; **Sean D. Gregory**, City of Columbus, State of Ohio; **Jason R. Robinson**, City of Columbus, State of Ohio; and **John Liu**, City of Columbus, State of Ohio, have invented certain new and useful improvements in **ACTIVE TEMPERATURE DIFFERENTIAL COMPENSATION FOR STRAIN GAGE BASED SENSORS**, for which an application is being made for Letters Patent of the United States.

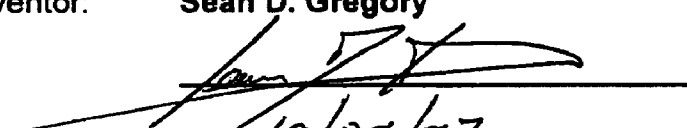
Whereas, Honeywell International Inc., a corporation organized and existing under the laws of the State of Delaware, and having its principal offices at 101 Columbia Road, POB 2245, Morristown, New Jersey, U.S.A., 07962, is desirous of acquiring the entire right, title and interest in and to said invention, said application and in, to and under any and all Letters Patent to be obtained therefor;

Now, therefore, for good and valuable consideration to us paid by the said Honeywell International Inc., the receipt of which is hereby acknowledged, I have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the said Honeywell International Inc., its successors and assigns, my entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all of my rights under any and all international conventions, treaties and/or agreements concerning patents to which the United States is a party, and I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to the above mentioned assignee in accordance herewith.


I further authorize said assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent, in its own name if desired, in any and all foreign countries, and additionally to claim the filing date of said United States application and/or otherwise take advantage of the provisions of any international convention, treaty and/or agreement.

I do hereby covenant and agree with the said assignee, its successors and assigns, that I will not execute any writing or do any act whatsoever conflicting with these presents, and that I or my executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said assignee, its successors and assigns, execute such additional writings and do such additional acts as said assignee, its successors and assigns, may deem necessary or desirable to perfect the assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, or any of and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

Full name of 1st Joint Inventor: **Michael E. Moran**
Inventor's Signature: 
Date: 22 Aug 07
Residence (City, State): **Marysville, Ohio**
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Citizenship: **USA**

Full name of 2nd Joint Inventor: **Sean D. Gregory**
Inventor's Signature: 
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Citizenship: USA

Full name of 3rd Joint Inventor: **Jason R. Robinson**

Inventor's Signature: 

Date: 8/21/2007

Residence (City, State): Columbus, Ohio

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Citizenship: USA

Full name of 4th Joint Inventor: John Liu
Inventor's Signature: John Liu
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